

METHODS FOR FORMING A THIN FILM ON AN INTEGRATED CIRCUIT DEVICE

ABSTRACT OF THE DISCLOSURE

Methods for forming a thin film on an integrated circuit device including providing energy to reactants in a deposition chamber to activate the reactants. The activated reactants are then deposited on the substrate to form a thin film on the substrate. The reactants selected may be selectively activated so that different thin films are formed in a single chamber thereby reducing processing time.